

CMOS STATIC RAM 64K (16K x 4-BIT)

IDT6198S IDT6198L

FEATURES:

- Optimized for fast RISC processors including the IDT79R3000
- Output Enable (OE) pin available for added system flexibility
- · High-speed (equal access and cycle times)
- Military: 20/25/35/45/55/70/85ns (max.)
- Commercial: 15/20/25/35ns (max.)
- · Low-power consumption
- IDT6198S
 - Active: 350mW (typ.) Standby 100µW (typ.)
- IDT6198L Active: 300mW (typ.)
- Active: 300mW (typ.) Standby: 30μW (typ.)
- JEDEC compatible pinout
- Battery back-up operation—2V data retention (L version only)
- 24-pin CERDIP, 24-pin plastic DIP, high-density 28-pin leadless chip carrier and 24-pin SOIC (gull-wing and Jbend)

- Produced with advanced CEMOS™ technology
- · Bidirectional data inputs and outputs
- · Military product compliant to MIL-STD-883, Class B

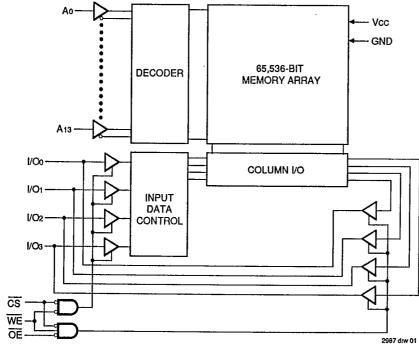
DESCRIPTION:

The IDT6198 is a 65,536-bit high-speed static RAM organized as 16K x 4. It is fabricated using IDT's high-performance, high-reliability technology—CEMOS. This state-of-the-art technology, combined with innovative circuit design techniques, provides a cost-effective approach for memory intensive applications. Timing parameters have been specified to meet the speed demands of the IDT79R3000 RISC processors.

The IDT6198 features two memory control functions: chip select (\overline{CS}) and output enable (\overline{OE}) . These two functions greatly enhance the IDT6198's overall flexibility in high-speed memory applications.

Access times as fast as 15ns are available, with typical power consumption of only 300mW. The IDT6198 offers a reduced power standby mode, IsB1, which enables the designer to considerably reduce device power requirements. This capability significantly decreases system power and

FUNCTIONAL BLOCK DIAGRAM



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MILITARY AND COMMERCIAL TEMPERATURE RANGES

DECEMBER 1990

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MILITARY AND COMMERCIAL TEMPERATURE RANGES

DESCRIPTION (Continued)

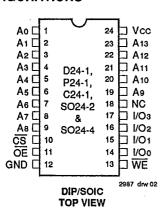
cooling levels, while greatly enhancing system reliability. The low-power version (L) also offers a battery backup data retention capability where the circuit typically consumes only 30µW when operating from a 2 volt battery.

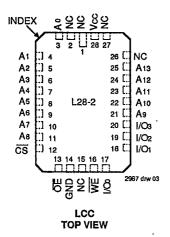
All inputs and outputs are TTL-compatible and operate from a single 5 volt supply.

The IDT6198 is packaged in either a 24-pin 300 mil CERDIP or plastic DIP, 28-pin leadless chip carrier or 24-pin guli-wing or J-bend small outline IC.

Military grade product is manufactured in compliance with the latest revision of MIL-STD-883, Class B, making it ideally suited to military temperature applications demanding the highest level of performance and reliability.

PIN CONFIGURATIONS





PIN DESCRIPTIONS

T-46-23-10

Name	Description
A0-A13	Address Inputs
ĊS	Chip Select
WE	Write Enable
ŌĒ	Output Enable
I/Oo-I/O3	Data Input/Output
Vcc	Power
GND	Ground
	2097 IN /

TRUTH TABLE(1)

Mode	CS	WE	ŌĒ	l⁄o	Power
Standby	Н	х	Х	High Z	Standby
Read	L	Н	L	Dout	Active
Write	L	L	Х	Din	Active
Read	L	Н	Н	High Z	Active

NOTE:

1. H = VIH, L = VIL, X = Don't Care

2987 tbl 02

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Rating	Com'l.	MII.	Unit
VTERM	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	٧
Та	Operating Temperature	0 to +70	-55 to +125	°Ç
TBIAS	Temperature Under Bias	-55 to +125	-65 to +135	°C
Тѕтс	Storage Temperature	-55 to +125	-65 to +150	ပ္
Pr	Power Dissipation	1.0	1.0	W
lout	DC Output Current	50	50	mA

NOTE:

Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

CAPACITANCE (TA = $+25^{\circ}$ C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
CIN	Input Capacitance	VIN = 0V	7	pF
Соит	Output Capacitance	Vout = 0V	7	pF

NOTE:

2987 tbi 04

1. This parameter is determined by device characterization, but is not production tested.

INTEGRATED DEVICE

38E D 4825771 0008194 8 MM IDT

IDT6198S/L CMOS STATIC RAM 64K (16K x 4-BIT)

MILITARY AND COMMERCIAL TEMPERATURE RANGES

RECOMMENDED DC OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	V
GND	Supply Voltage	0	0	0	V
VIH	Input High Voltage	2.2	_	6.0	٧
VIL	Input Low Voltage	-0.5 ⁽¹⁾		0.8	٧

NOTE: 2987 tbl 05 1. VIL (min.) = -3.0V for pulse width less than 20ns.

RECOMMENDED OPERATING TEMPERATURE AND SUPPLY VOLTAGE

Grade	Temperature	GND	Vcc
Military	-55°C to +125°C	ov	5V ± 10%
Commercial	0°C to +70°C	οV	5V ± 10%

DC ELECTRICAL CHARACTERISTICS

 $VCC = 5.0V \pm 10\%$

				IDT6	198S	IDT6	198L	
Symbol	Parameter	Test Condition	Min.	Max.	Min.	Max.	Unit	
iLi	Input Leakage Current	Vcc = Max., Vin = GND to Vcc	MIL. COM'L.	_	10 5	_	5 2	μА
lLO	Output Leakage Current	Vcc = Max., \overline{CS} = VIH, Vout = GND to Vcc	MIL. COM'L.	_	10 5	_	5 2	μА
Vol	Output Low Voltage	IOL = 10mA, Vcc = Min.			0.5	_	0.5	V
		lot = 8mA, Vcc = Min.			0,4	-	0.4	
Vон	Output High Voltage	IOL = -4mA, VCC = Min.		2.4		2.4		V

2967 tbl 07

DC ELECTRICAL CHARACTERISTICS(1)

 $(VCC = 5V \pm 10\%, VLC = 0.2V, VHC = VCC - 0.2V)$

	·			BS15 BL15		8S20 BL20		3S25 BL25		3S35 3L35		3S45 3L45	1	5/70/85 5/70/85	
Symbol	Parameter	Power	Com'l.	Mil.	Com'l.	MII.	Com'i.	Mil.	Com'l.	Mil.	Com'i.	MII.	Com'l.	Mil.	Unit
	Operating Power Supply Current	S	110	_	100	110	100	110	100	110	_	110	-	110	mA
	CS = ViL, Outputs Open Vcc = Max., f = 0 ⁽²⁾	L	75	_	70	80	70	80	85	95	_	95	-	95	
lcc2	Dynamic Operating Current	S	135		130	160	135	155	125	140	-	140	_	140	mA
	CS = VIL, Outputs Open Vcc = Max., f = fMax ⁽²⁾	L	125	_	115	130	105	120	105	115	_	110	_	110	
ISB	Standby Power Supply Current (TTL Level)	S	60		55	70	55	60	45	500	-	50	_	50	mΑ
	CS ≥ VIH, VCC = Max., Outputs Open, f = fMAX ⁽²⁾	L	45	_	40	50	35	40	35	40	_	35	_	35	
ISB1	Full Standby Power Supply Current (CMOS	S	20		. 15	25	15	20	15	20	_	20	_	20	mA
L. Vo	Level) CS ≥ VHC, VCC=Max., VIN ≥ VHC or VIN ≤ VLC, f = 0 ⁽²⁾	L	1.5	_	0.5	1.5	0.5	1.5	0.5	1.5	_	1.5		1.5	

2987 tbl 06

All values are maximum guaranteed values.
 At f = fMAX address and data inputs are cycling at the maximum frequency of read cycles of 1/tRc. f = 0 means no input lines change.

IDT6198S/L

T-46-23-10
MILITARY AND COMMERCIAL TEMPERATURE RANGES

CMOS STATIC RAM 64K (16K x 4-BIT)

DATA RETENTION CHARACTERISTICS OVER ALL TEMPERATURE RANGES

(L Version Only) VLc = 0.2V, VHC = VCC - 0.2V

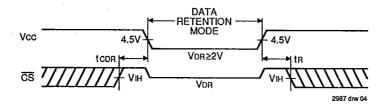
						/p. ⁽¹⁾ cc @		lax. cc @		
Symbol	mbol Parameter Test Condition		dition	Min.	2,0v	3.0V	2.0V	3.0V	Unit	
Vdr	Vcc for Data Retention	_		2.0	_		-	_	V	
ICCOR	Data Retention Current		MIL. COM'L.	_	10 10	15 15	600° 150	900 225	μА	
tCDR ⁽³⁾	Chip Deselect to Data Retention Time	CS≥VHC VIN≥VHCo	r ≤ VLC	0		_	_	_	ns	
tR ⁽³⁾	Operation Recovery Time	1	Ī	tRC ⁽²⁾			_		ns	
LI ⁽³⁾	Input Leakage Current	1	Ī	_	_	·	2	2	μА	

NOTES:

- 1. TA = +25°C.
- 2. tRc = Read Cycle Time.
- 3. This parameter is guaranteed, but not tested.

2967 tbl 09

LOW Vcc DATA RETENTION WAVEFORM





AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	5ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	See Figures 1 and 2

2987 tbl 10

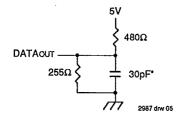


Figure 1. Output Load

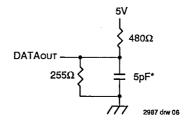


Figure 2. Output Load (for tol.z, tcl.z, tohz, twhz, tchz and tow)

*Includes scope and jig capacitances

IDT6198S/L CMOS STATIC RAM 64K (16K x 4-BIT)

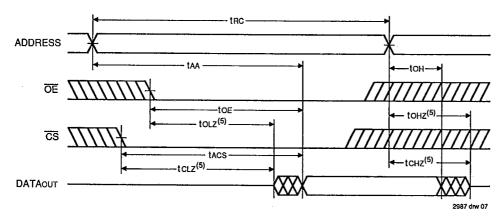
MILITARY AND COMMERCIAL TEMPERATURE RANGES

AC ELECTRICAL CHARACTERISTICS (Vcc = 5.0V ± 10%, All Temperature Ranges)

		3S15 ⁽¹⁾ 3L15 ⁽¹⁾		8S20 8L20		8S25 8L25		8S35 8L35				70/85 ⁽²⁾ 70/85 ⁽²⁾	
Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Uni
					•						•		
Time	15		20		25		35		45/55	_	70/85	_	ns
cess Time		15		19	—	25	<u> </u>	35		45/55	_	70/85	ns
Access Time	-	15		20		25		35	-	45/55	_	70/85	ns
to Output in Low Z ⁽³⁾	5		5	_	5		5		5	_	5	_	ns
ole to Output Valid		8	_	9	-	11	_	18	-	25/35		45/55	ns
ole to Output in Low Z ⁽³⁾	5	_	5	_	5	_	5	_	5		5	_	ns
to Output in High Z ⁽³⁾	2	7	2	8	2	10	2	14	_	15/20	_	25/30	ns
ble to Output in High Z ⁽³⁾	2	7	2	8	2	9	2	15	_	15/20	_	25/30	ns
from Address Change	5		5	_	2	_	5	-	5	_	5	_	ns
to Power Up Time ⁽³⁾	0	_	0	_	0		0		0	_	0	_	ns
ect to Power Down Time ⁽³⁾	_	15	1	20		25	_	35	1_	45/55		70/85	ns
	to Power Down Time ⁽³⁾												29

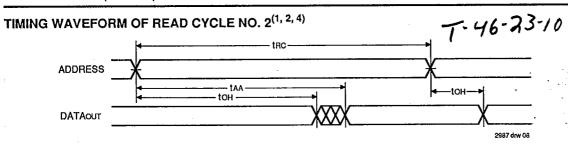
- 1. 0° to +70°C temperature range only.
 2. -55°C to +125°C temperature range only.
 3. This parameter guaranteed but not tested.

TIMING WAVEFORM OF READ CYCLE NO. 1⁽¹⁾

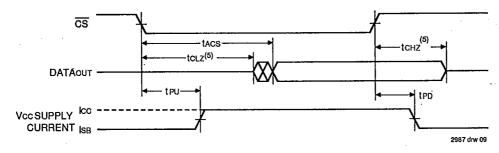


- NOTES:
 1. WE is high for Read cycle.
 2. Device is continuously selected, \overline{CS} = Vil..
 3. Address valid prior to or coincident with \overline{CS} transition low.
 4. \overline{OE} = Vil..
 5. Transition is measured ±200mV from steady state voltage.

MILITARY AND COMMERCIAL TEMPERATURE RANGES



TIMING WAVEFORM OF READ CYCLE NO. $3^{(1, 3, 4)}$



NOTES:

1. WE is high for Read cycle.

2. Device is continuously selected, $\overline{CS} = V_{IL}$.

3. Address valid prior to or coincident with \overline{CS} transition low.

4. $\overline{OE} = V_{IL}$.

5. Transition is measured ±200mV from steady state voltage.



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MILITARY AND COMMERCIAL TEMPERATURE RANGES

CMOS STATIC RAM 64K (16K x 4-BIT)

AC ELECTRICAL CHARACTERISTICS (Vcc = 5.0V ± 10%, All Temperature Ranges)

			3S15 ⁽¹⁾ 3L15 ⁽¹⁾	6198S20 6198L20		6198S25 6198L25		6198S35 6198L35				6198\$70/85 ⁽²⁾ 6198L70/85 ⁽²⁾		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit
Write C	ycle						-			•	<u> </u>			-
twc	Write Cycle Time	14	<u> </u>	17		20	<u> </u>	30	Γ-	40/50	_	60/75	F	ns
tcw	Chip Select to End of Write	14	_	17	_	20	_	25	_	35/50	_	60/75	_	ns
taw	Address Valid to End of Write	14	_	17		20	-	25	_	35/50	_	60/75		ns
tas	Address Set-up Time	0	_	0		0	_	0	-	0	_	0		ns
tWP	Write Pulse Width	14		17	_	20	_	25		35/50	_	60/75	_	ns
twr	Write Recovery Time	0	_	0		0	_	0	_	0	-	0	_	ns
twHz	Write Enable to Output in High Z ⁽³⁾	Τ	5	_	6		7	_	10	_	15/25	_	30/40	ns
tow	Data Valid to End of Write	10	-	10	_	13	_	15	_	20/25		30/35	_	ns
tDH	Data Hold Time	0	_	0	_	. 0		0		0	-	0		ns
tow	Output Active from End of Write ⁽³⁾	5	_	5	_	5		5	_	5		5	_	ns

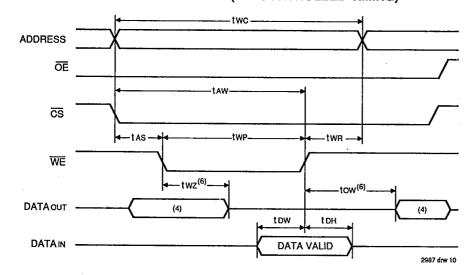
NOTES:

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- 0° to +70°C temperature range only.
 -55°C to +125°C temperature range only. 3. This parameter guaranteed but not tested.

2987 tbf 12

TIMING WAVEFORM OF WRITE CYCLE NO. 1 (WE CONTROLLED TIMING)(1, 2, 3, 7)



- NOTES:

 1. WE or CS must be high during all address transitions.

 2. A write occurs during the overlap (tcw twe) of a low CS and a low WE.

 3. two is measured from the earlier of CS or WE going high to the end of the write cycle.

 4. During this period, I/O pins are in the output state so that the input signals must not be applied.

 5. If the CS low transition occurs simultaneously with or after the WE low transition, the outputs remain in a high impedance state.

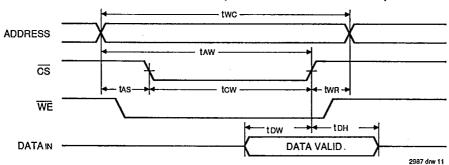
 6. Transition is measured ±200mV from steady state.

 7. If OE is low during a WE controlled write cycle, the write pulse width must be the larger of two or (twHz + tow) to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If OE is high an WE controlled write cycle, this requirement does not apply and the write pulse can be as short as the specified two. as the specified twp. 8. OE = VIH.

T-46-23-10

IDT6198S/L CMOS STATIC RAM 64K (16K x 4-BIT) **MILITARY AND COMMERCIAL TEMPERATURE RANGES**

TIMING WAVEFORM OF WRITE CYCLE NO. 2 (CS CONTROLLED TIMING)(1, 2, 3, 5, 8)



NOTES:

- NOTES:

 1. WE or CS must be high during all address transitions.

 2. A write occurs during the overlap (tow twe) of a low CS and a low WE.

 3. twn is measured from the earlier of CS or WE going high to the end of the write cycle.

 4. During this period, I/O pins are in the output state so that the input signals must not be applied.

 5. If the CS low transition occurs simultaneously with or after the WE low transition, the outputs remain in a high impedance state.

 6. Transiting is measured ±200mV from steady state.
- Transition is measured ±200mV from steady state.

 If OE is low during a WE controlled write cycle, the write pulse width must be the larger of twp or (twpz + tow) to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If OE is high an WE controlled write cycle, this requirement does not apply and the write pulse can be as short as the specified twp.

ORDERING INFORMATION

